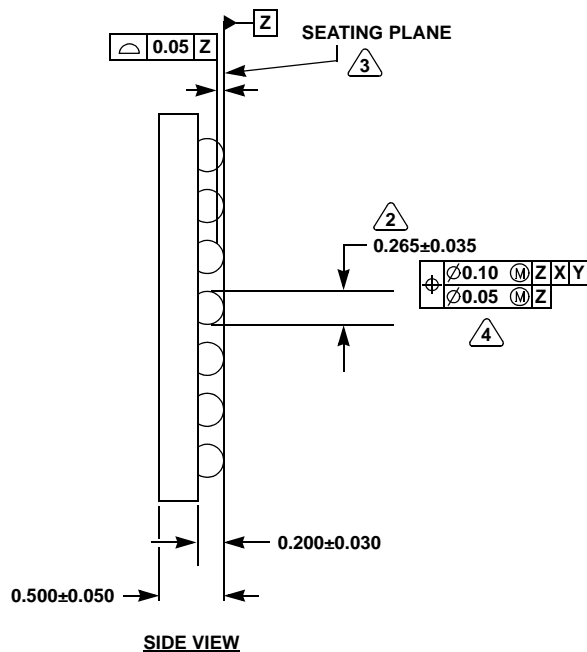
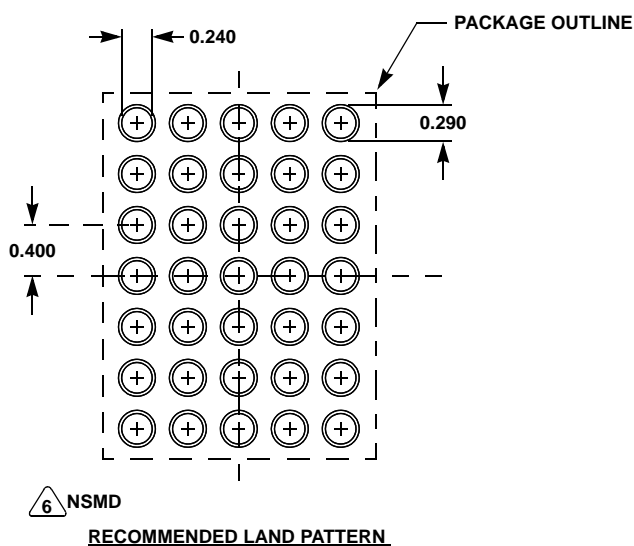
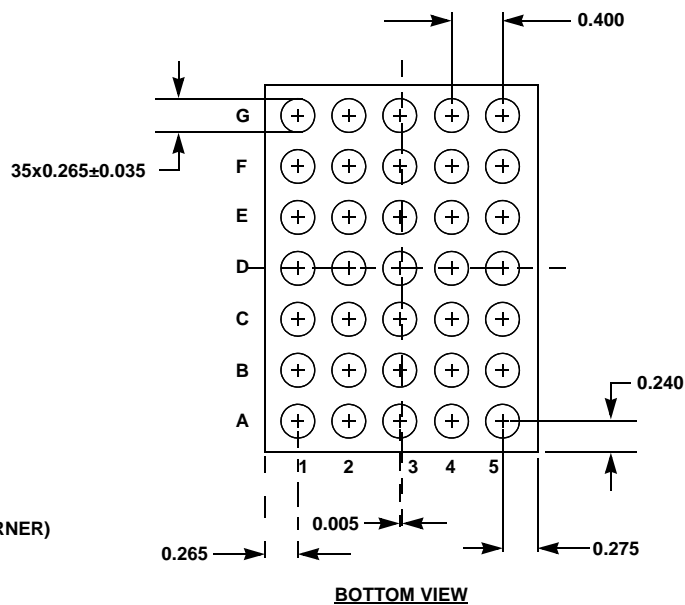
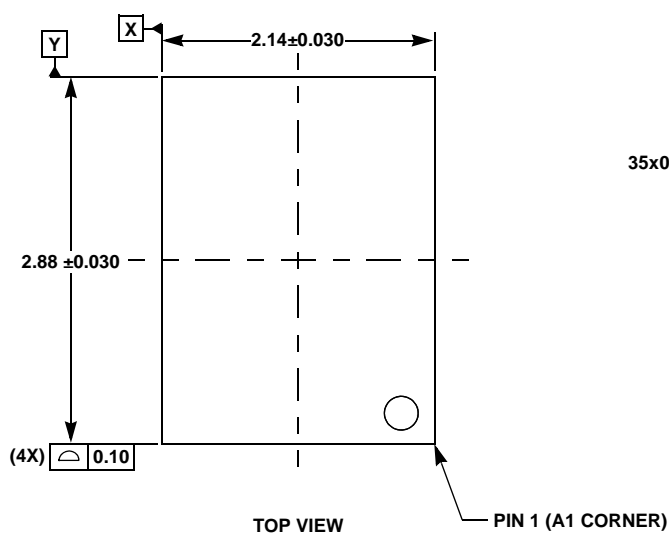


## Package Outline Drawing

### W5x7.35

35 BALL WAFER LEVEL CHIP SCALE PACKAGE (WLCSP 0.4mm Pitch)

Rev 0, 11/14



#### NOTES:

1. Dimensions and tolerance per ASME Y 14.5M - 1994.
- ③ Dimension is measured at the maximum bump diameter parallel to primary datum Z.
- ③ Primary datum Z and seating plane are defined by the spherical crowns of the bump.
- ④ Bump position designation per JESD 95-1, SPP-010.
5. All dimensions are in millimeters.
- ⑥ NSMD refers to non-solder mask defined pad design per Intersil Techbrief [TB451](#).